

PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION

Part Number:

0739446004

Status:

Active

Overview:

HDM Backplane Connector System

Description:

HDM Board-to-Board Backplane Header, Vertical, SMC, Solder Tail, Guide Pin Option, Guide Post Location B, Polarizing Key Position C, 72 Circuits

Documents:

3D Model

Product Specification PS-73670-9999 (PDF)

3D Model (PDF)

Packaging Specification PK-70873-0818 (PDF)

Drawing (PDF)

RoHS Certificate of Compliance (PDF)

Agency Certification

CSA

LR19980

UL

E29179

General

Product Family

Backplane Connectors

Series

73944

Application

Backplane

Component Type

PCB Header

Overview

HDM Backplane Connector System

Product Name

HDM

UPC

756054803196

Physical

Circuits (Loaded)

72

Circuits (maximum)

72

Color - Resin

Black, Natural

Durability (mating cycles max)

250

First Mate / Last Break

No

Flammability

94V-0

Guide to Mating Part

Yes

Keying to Mating Part

Yes

Material - Metal

Phosphor Bronze, Stainless Steel

Material - Plating Mating

Gold

Material - Plating Termination

Tin

Material - Resin

High Temperature Thermoplastic

Net Weight

6.097/g

Number of Columns

12

Number of Pairs

Open Pin Field

Number of Rows

6

Orientation

Vertical

PC Tail Length

3.50mm

PCB Locator

No

PCB Retention

None

PCB Thickness - Recommended

2.50mm

Packaging Type

Tube

Pitch - Mating Interface

2.00mm

Pitch - Termination Interface

2.00mm

Plating min - Mating

0.762µm

Plating min - Termination

2.540µm

Polarized to PCB

No

Stackable

Yes

Surface Mount Compatible (SMC)

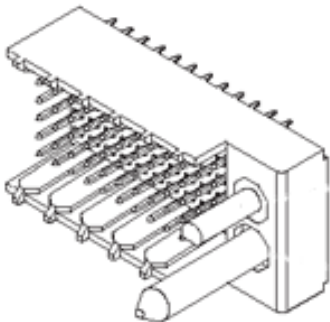
Yes

Temperature Range - Operating

-55° to +105°C

Termination Interface: Style

Through Hole



Series image - Reference only

EU ELV

Not Relevant

EU RoHS

Compliant

China RoHS

REACH SVHC

Not Contained Per -
ED/71/2019 (16 July
2019)

Halogen-Free

Status

Low-Halogen

For more information, please visit [Contact US](#)

China ROHS

Green Image

ELV

Not Relevant

RoHS Phthalates

Not Contained

Search Parts in this Series

73944 Series

Mates With

73632 HDM+ Board-to-Board Daughtercard Receptacle. 73780 HDM Board-to-Board Daughtercard Receptacle

Application Tooling | FAQ

Tooling specifications and manuals are found by selecting the products below. Crimp Height Specifications are then contained in the Application Tooling Specification document.

Global

Description	Product #
Extraction Tool	621001000
Backplane Insertion	621001400
Signal Contact Tool	
Backplane Signal	622008502
Insertion Module	
Press-In Tool for 2.00mm Pitch HDM*	
Board-to-Board	
Backplane Header	

Electrical

Current - Maximum per Contact	1.0A
Data Rate	1.0 Gbps
Real Signals (per 25mm)	75
Shielded	No
Voltage - Maximum	250V AC

Material Info

Reference - Drawing Numbers

Packaging Specification	PK-70873-0818
Product Specification	PS-73670-9999
Sales Drawing	SD-73944-001

This document was generated on 12/10/2019

PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

Molex:

73944-6004